

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2023/0231295 A1 Yoon et al.

Jul. 20, 2023 (43) Pub. Date:

(54) ELECTRONIC DEVICE

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Appl. No.: 18/152,422

(22)Filed: Jan. 10, 2023

(30)Foreign Application Priority Data

Jan. 19, 2022 (KR) 10-2022-0007888 (KR) 10-2022-0048261

Publication Classification

(51) Int. Cl. H01Q 1/22

(2006.01)

 $H01\widetilde{Q}$ 21/00

(2006.01)

U.S. Cl. (52)CPC H01Q 1/2283 (2013.01); H01Q 21/0025

(2013.01)

(57)ABSTRACT

An electronic device is provided. An electronic device includes a radio frequency integrated circuit (RFIC) chip, and an antenna array electrically connected to the RFIC chip, the antenna array including a first face and a second face facing each other in a first direction, and a third face and a fourth face connecting the first and second faces to each other and facing each other in a second direction intersecting the first direction, the antenna array including a plurality of substrates sequentially stacked in a third direction intersecting a plane defined by the first and second directions, first and second antenna modules on the plurality of substrates and sequentially arranged along the first direction, a first metal partition-wall including at least one metal via extending through the plurality of substrates in the third direction, and a second metal partition-wall surrounding the first to fourth faces.

